



Microbonds

COOKSON ELECTRONICS AND MICROBONDS FORM ALLIANCE ON PLASKON® AND X-WIRE™ TECHNOLOGY

Alpharetta, GA. & Toronto, CANADA, (July 5, 2006)-- Cookson Electronics – Semiconductor Products, a division of Cookson Group plc and Microbonds Inc. (a private Canadian corporation) today announce a co- development project to align the technology roadmaps of Microbonds’ insulated wire bonding technology known as X-Wire™ Technology, with the Plaskon® molding compounds of Cookson Electronics – Semiconductor Products division.

Cookson Electronics is a premier supplier of advanced materials for the Semiconductor Packaging industry, providing integrated technology solutions for a vast array of the most advanced semiconductor packages in the market.

Microbonds’ X-Wire™ Technology insulates gold and copper bonding wires used to connect the silicon die with the package device. Insulating bonding wires enables a number of industry trends currently impeded by the limitations of bare bonding wires which short out the device when they touch. Specifically in order to accommodate industry trends toward thinner diameter gold wires, longer wires, stacked die for wireless applications and other 3D packaging requirements, insulating the bonding wires provides the package designer and the assembler with more options to achieve their technical and economic objectives.

The joint technical effort between the Plaskon® family of mold compounds and Microbonds X-Wire™ Technology will provide common customers with cost effective wire bond and package molding flexibilities.

“The ongoing need to cost effectively mold ever smaller package sizes and types, while maintaining or increasing electrical and yield performance, is beginning to push the limits of molding bare bonding wires. Microbonds’ X-Wire Technology is a complementary and innovative solution that enhances molding capabilities that we are happy to support for the mutual benefit of our customers and the industry”, said Scott Craig, Senior VP & General Manager, Cookson Electronics - Semiconductor Products.

John Scott, CEO of Microbonds added, “With the support of industry leaders like Cookson, our technology will continue to evolve, and customers can have confidence that insulated bonding wire is maturing into a robust and scalable interconnect option. Specifically, the integration of X-Wire Technology with the Plaskon® leading molding compounds will provide customers new flexibility in the development and assembly of high performance-to-cost packaged ICs.”

About Cookson Electronics – Semiconductor Products

Cookson Electronics – Semiconductor Products, a division of the Cookson Group plc, is the world's premier supplier of leading edge technologies for a vast array of applications of the Semiconductor Packaging Industry. With annual sales in excess of \$1 billion, Cookson Electronics is the 3rd largest materials supplier to global electronics manufacturers industry. For more information, see www.cooksonelectronics.com.

About Microbonds

Microbonds, Inc. is the leading developer and licensor of insulated wire bonding technologies for use in the design and assembly of microelectronic devices. The company's X-Wire™ Technology has recently received a Technology Innovation Award from SEMI®.

For more information, see www.microbonds.com

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